

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

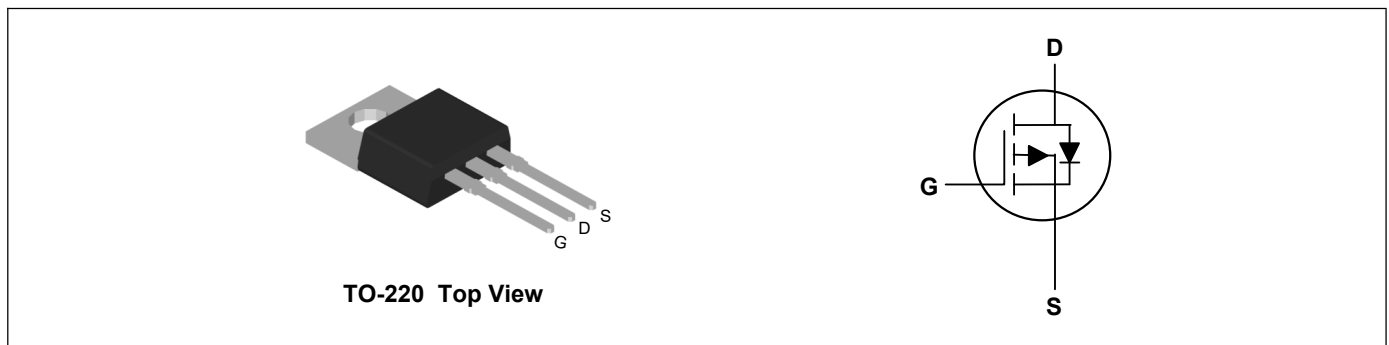
Product Summary



V_{DS}	-60	V
I_D	-58	A
$R_{DS(ON)}$ (at $V_{GS}=-10V$)	16	m Ω
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	18	m Ω

Applications

- High Frequency Point-of-Load, Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch



Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	$I_D@T_C=25^\circ\text{C}$	-58	A
Continuous Drain Current ¹	$I_D@T_C=100^\circ\text{C}$	-49	A
Pulsed Drain Current ²	I_{DM}	-250	A
Single Pulse Avalanche Energy ³	EAS	450	mJ
Avalanche Current	I_{AS}	-41	A
Total Power Dissipation ⁴	$P_D@T_C=25^\circ\text{C}$	114	W
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	---	62	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	---	1.1	$^\circ\text{C}/\text{W}$

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250uA	-60	---	---	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-20A	---	12	16	mΩ
		V _{GS} =-4.5V, I _D =-10A	---	15	18	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =-250uA	-1.0	---	-2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =-60V, V _{GS} =0V	---	---	-1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
Total Gate Charge	Q _g	V _{DS} =-30V, V _{GS} =-10V, I _D =-50A	---	94	---	nC
Gate-Source Charge	Q _{gs}		---	18	---	
Gate-Drain Charge	Q _{gd}		---	24	---	
Turn-On Delay Time	T _{d(on)}	V _{DS} =-30V, V _{GS} =-10V, R _G =6Ω	---	53	---	ns
Rise Time	T _r		---	19	---	
Turn-Off Delay Time	T _{d(off)}		---	221	---	
Fall Time	T _f		---	61	---	
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V, f=1MHz	---	4710	---	pF
Output Capacitance	C _{oss}		---	373	---	
Reverse Transfer Capacitance	C _{rss}		---	336	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V, I _S =-17A	---	---	-1.2	V

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V_{DD}=-48V, V_{GS}=-10V, L=0.1mH
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

Typical Characteristics

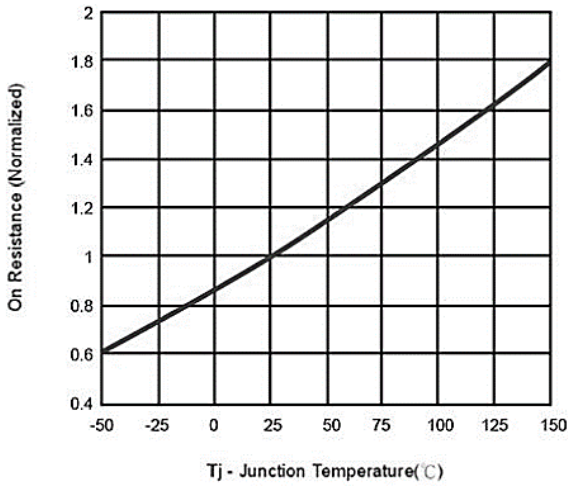


Fig.1 On Resistance Vs Junction Temperature

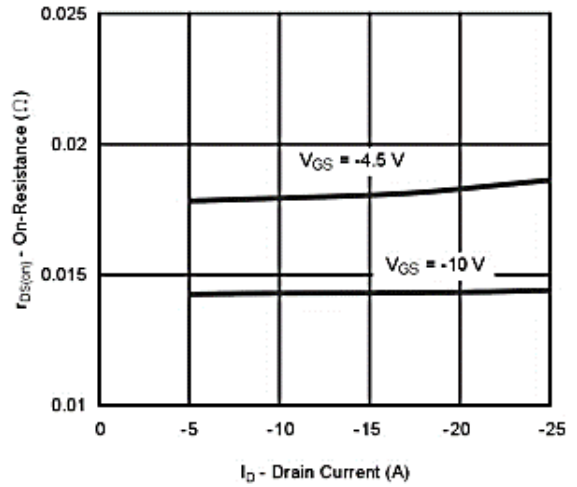


Fig.2 On-Resistance Vs. Drain Current

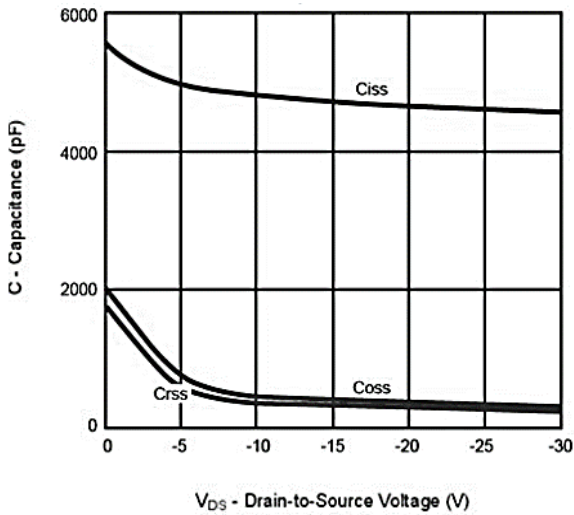


Fig.3 Capacitance

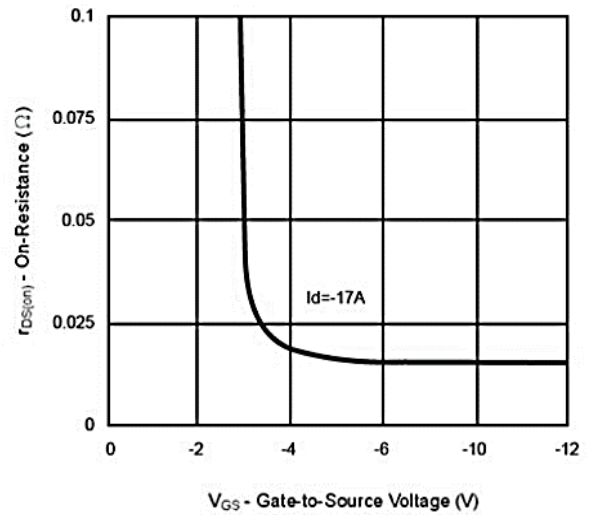


Fig.4 On-Resistance Vs. Gate-to-Source Voltage

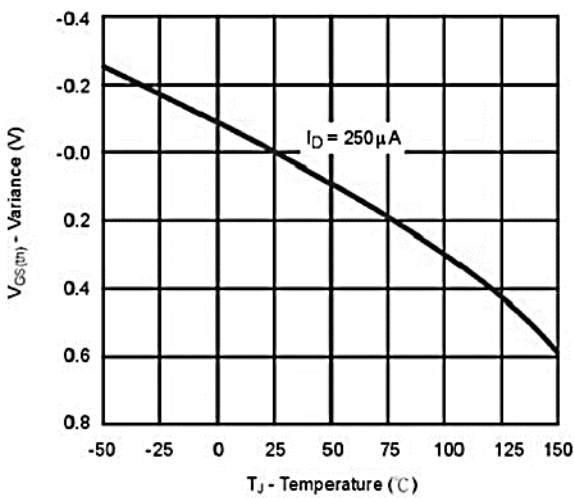


Fig.5 Threshold Voltage

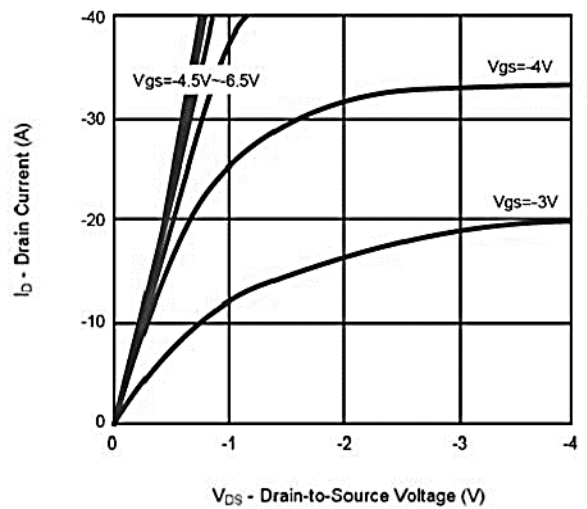


Fig.6 On-Region Characteristics

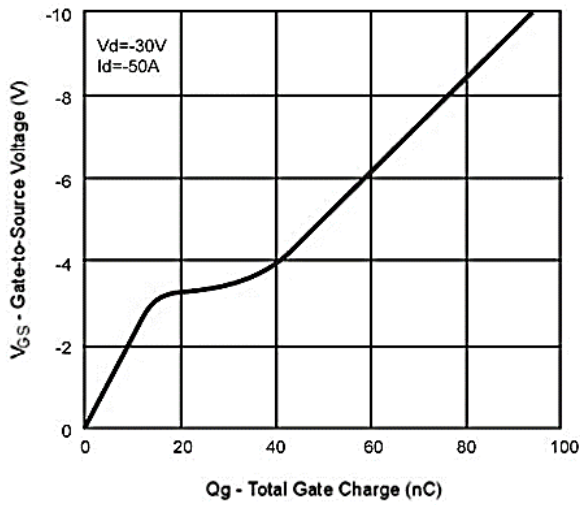


Fig.7 Gate Charge

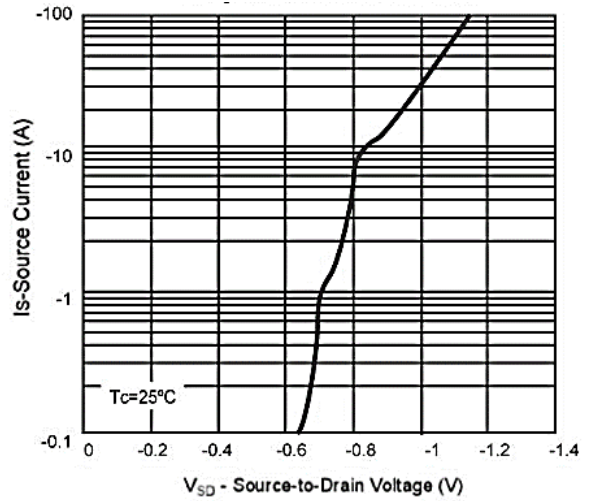


Fig.8 Body-diode Characteristic

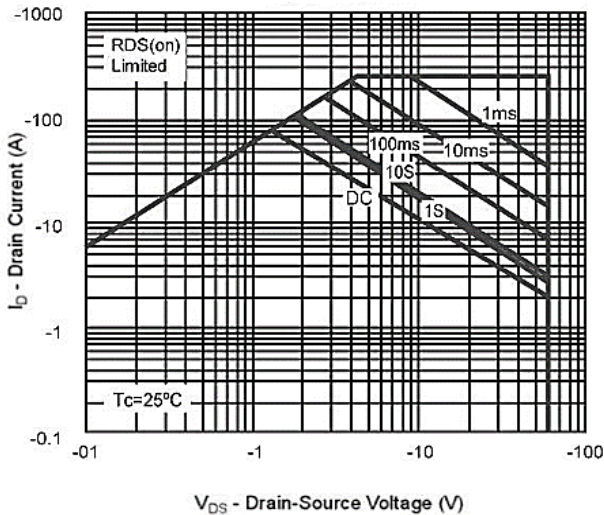


Fig.9 Safe Operating Area

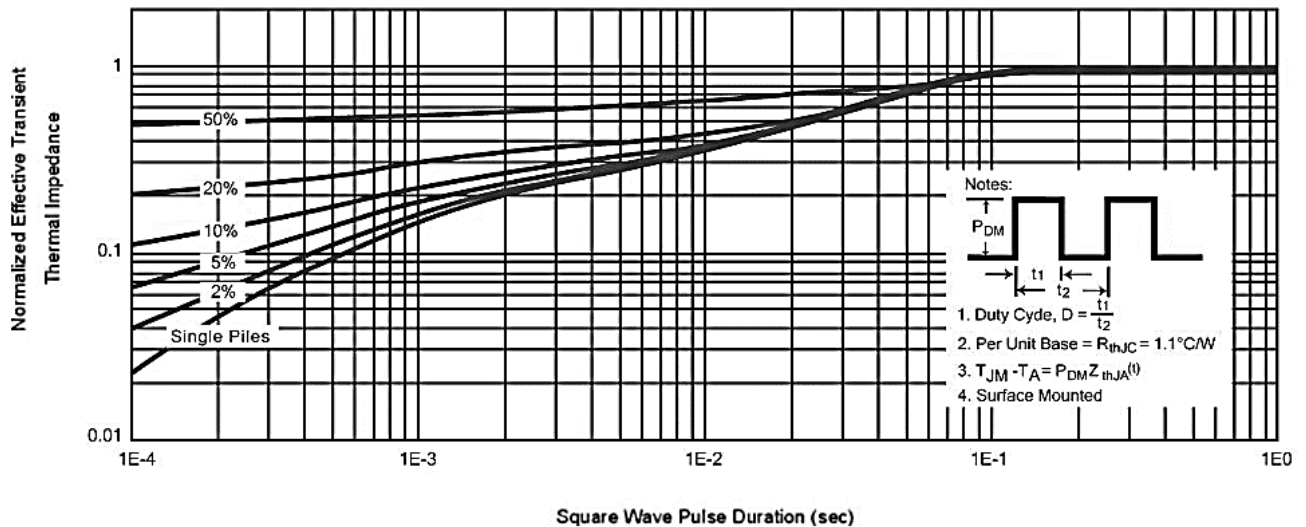
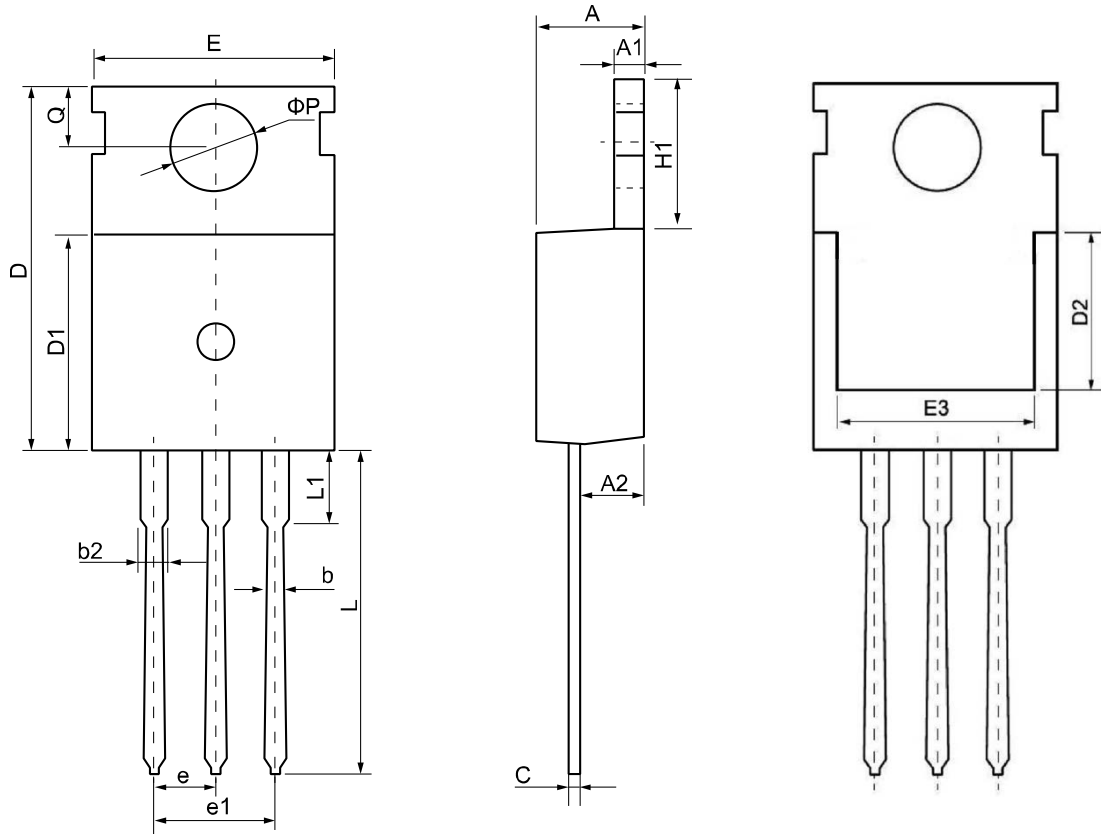


Fig.10 Normalized Maximum Transient Thermal Impedance

TO-220 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	4.30	4.55	4.75	E	9.65	10.00	10.25
A1	1.15	1.30	1.45	E3	7.00	--	--
A2	2.20	2.40	2.60	e	2.54 BSC		
b	0.70	0.80	0.95	e1	5.08 BSC		
b2	1.17	1.27	1.47	H1	6.30	6.50	6.80
c	0.40	0.50	0.65	L	12.70	13.50	14.10
D	15.30	15.60	15.90	L1	--	3.20	3.95
D1	8.90	9.10	9.35	phi P	3.40	3.60	3.80
D2	5.50	--	--	Q	2.60	2.80	3.00